

ABSTRACT OF THE DISCLOSURE

A semiconductor device which comprises a substrate and a semiconductor element mounted thereon through bumps by the so-called flip chip method, and in which the
5 semiconductor element has been encapsulated more easily and with higher certainty. A semiconductor device comprising a substrate and a semiconductor element mounted thereon through bumps, wherein the semiconductor element has been encapsulated by coating the back and the edges of the
10 semiconductor element with a thermosetting sheet material having tackiness. Preferably, the tackiness of the sheet material as measured at time of use is from 2 to 15 in terms of ball tack.